



Material Content Data Sheet



Sales Product Name		ITS4142N		Issued		29. August 2013		
MA#		MA001123604						
Package		PG-SOT223-4-23		Weight*		113.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.309	2.03	2.03	20274	20274
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		92	
	non noble metal	titanium	7440-32-6	0.052	0.05		458	
	non noble metal	chromium	7440-47-3	0.156	0.14		1373	
	non noble metal	copper	7440-50-8	51.895	45.55	45.75	455607	457530
wire	noble metal	gold	7440-57-5	0.239	0.21	0.21	2099	2099
encapsulation	organic material	carbon black	1333-86-4	0.449	0.39		3946	
	plastics	brominated resin	-	0.562	0.49		4933	
	inorganic material	antimonytrioxide	1309-64-4	1.124	0.99		9865	
	plastics	epoxy resin	-	10.225	8.98		89774	
	inorganic material	silicondioxide	60676-86-0	43.823	38.47	49.32	384744	493262
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12853	12853
plating	noble metal	silver	7440-22-4	0.815	0.72	0.72	7152	7152
glue	plastics	epoxy resin	-	0.136	0.12		1195	
	noble metal	silver	7440-22-4	0.642	0.56	0.68	5635	6830
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com